

# **Maximum Ratings** ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	40	V
Average Rectified Output Current	lo	0.5	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	14	A

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R <sub>θJA</sub>	135	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	$R_{ ext{ heta}JA}$	80	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

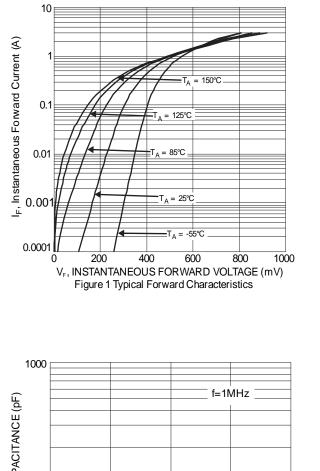
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

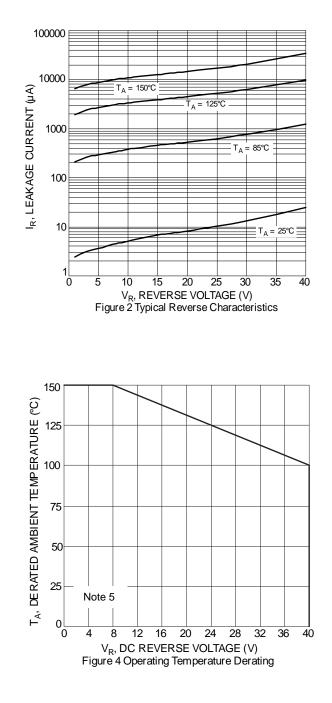
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	VF	-	0.305	0.36	V	I <sub>F</sub> = 0.1A
		-	0.415	0.46		I <sub>F</sub> = 0.5A
		-	0.34	-		$I_F = 0.5A, T_J = +125^{\circ}C$
Leakage Current (Note 7)	I <sub>R</sub>	-	-	15	μA	V <sub>R</sub> = 10V
		-	-	75		$V_R = 40V$
Junction Capacitance	CT	-	35	-	pF	$V_{R} = 4V, f = 1.0MHz$

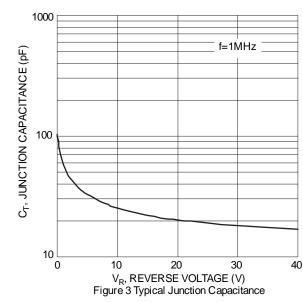
 Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
Device mounted on FR-4 PCB, 2oz. 1 square inch Copper.
Short duration pulse test used to minimize self-heating effect. Notes:



# SDM05U40CSP



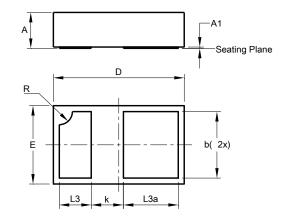






### **Package Outline Dimensions**

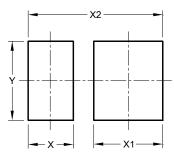
Please see http://www.diodes.com/package-outlines.html for the latest version.



X3-WLB1006-2				
Dim	Min	Max	Тур	
Α	0.25	0.30	0.275	
A1	0.00	0.01	-	
b	0.450	0.550	0.500	
D	0.95	1.05	1.000	
Е	0.55	0.65	0.600	
k	-	-	0.288	
L3	0.194	0.294	0.244	
L3a	0.350	0.450	0.400	
R	-	-	0.100	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)	
Х	0.332	
X1	0.507	
X2	0.989	
Y	0.579	



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